

LH231100B

NMOS 1M (128K × 8) Mask Programmable ROM

FEATURES

- 131,072 × 8 bit organization
- Access time: 200 ns (MAX.)
- Power consumption:
Operating: 550 mW (MAX.)
- Mask-programmable $OE_1/\overline{OE}_1/DC$ and $OE_2/\overline{OE}_2/DC$
- Fully static operation
- TTL compatible I/O
- Three-state outputs
- Single +5 V power supply
- Package:
32-pin, 600-mil DIP
(32-pin compatible to 28-pin 1M mask ROM specific pinout)

DESCRIPTION

The LH231100B is a mask programmable ROM organized as 131,072 × 8 bits. It is fabricated using silicon-gate NMOS process technology.

PIN CONNECTIONS

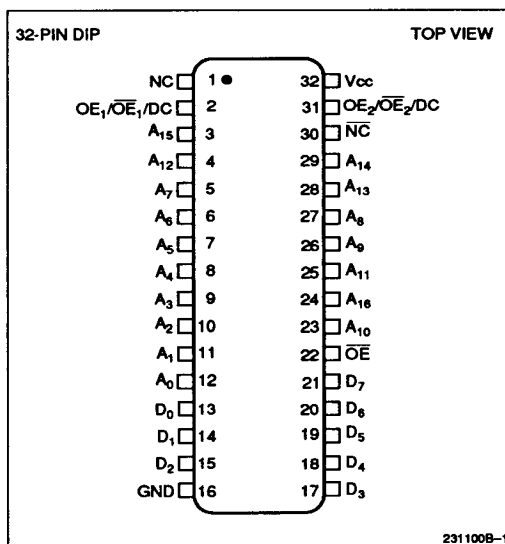


Figure 1. Pin Connections for DIP Package

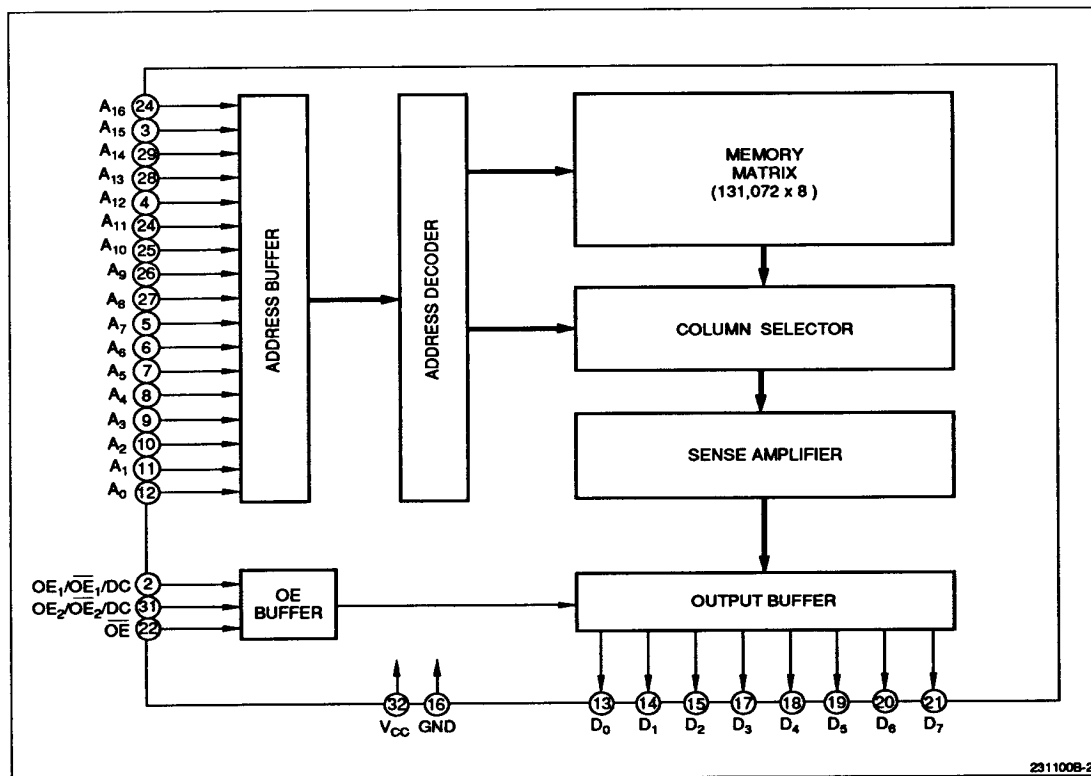


Figure 2. LH231100B Block Diagram

PIN DESCRIPTION

SIGNAL	PIN NAME	NOTE
A ₀ - A ₁₆	Address input	
D ₀ - D ₇	Data output	
OE ₁ /OE ₁ /DC OE ₂ /OE ₂ /DC	Output enable input or Don't Care connection	1

SIGNAL	PIN NAME	NOTE
V _{CC}	Power supply (+5 V)	
GND	Ground	

NOTE:

1. Active level of output enable is mask programmable. When DC is selected, it is fixed to an active level. (However, it is recommended to apply either "High" or "Low" to the DC pin).

TRUTH TABLE

OE	OE ₁ /OE ₁	OE ₂ /OE ₂	MODE	D ₀ - D ₇	SUPPLY CURRENT	NOTE
H	X	X	Non selected	High-Z	Operating (I _{CC})	1
X	L/H	X				
X	X	L/H				
L	H/L	H/L	Selected	DOUT		

NOTE:

1. X = H or L

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	RATING	UNIT	NOTE
Supply voltage	V _{CC}	-0.3 to +7.0	V	1
Input voltage	V _{IN}	-0.3 to +7.0	V	
Output voltage	V _{OUT}	-0.3 to +7.0	V	
Operating temperature	T _{opr}	0 to +70	°C	
Storage temperature	T _{stg}	-55 to +150	°C	

NOTE:

1. The maximum applicable voltage on any pin with respect to GND.

RECOMMENDED OPERATING CONDITIONS (T_A = 0 to +70°C)

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Supply voltage	V _{CC}	4.5	5.0	5.5	V

DC CHARACTERISTICS (V_{CC} = 5 V ± 10%, T_A = 0 to +70°C)

PARAMETER	SYMBOL	CONDITIONS	MIN.	TYP.	MAX.	UNIT	NOTE
Input "Low" voltage	V _{IL}		-0.3		0.8	V	
Input "High" voltage	V _{IH}		2.2		V _{CC} + 0.3	V	
Output "Low" voltage	V _{OL}	I _{OL} = 1.6 mA			0.4	V	
Output "High" voltage	V _{OH}	I _{OH} = -400 μA	2.4			V	
Input leakage current	I _{LI}	V _{IN} = 0 V to V _{CC}			10	μA	
Output leakage current	I _{LO}	V _{OUT} = 0 V to V _{CC}			10	μA	1
Operating current	I _{CC}	t _{RC} = 200 ns			100	mA	2

NOTES:

1. $\overline{OE}/\overline{OE}_1/\overline{OE}_2 = V_{IH}$ or $OE_1/OE_2 = V_{IL}$
 2. V_{IN} = V_{IH}/V_{IL}, outputs open

AC CHARACTERISTICS (V_{CC} = 5 V ± 10%, T_A = 0 to +70°C)

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	NOTE
Read cycle time	t _{RC}	200			ns	
Address access time	t _{AA}			200	ns	
Output enable access time	t _{OE}			80	ns	
Output hold time	t _{OH}	10			ns	
OE to output in High-Z	t _{OHZ}			80	ns	1

NOTE:

1. This is the time required for the output to become high impedance.

AC TEST CONDITIONS

PARAMETER	RATING
Input voltage amplitude	0.6 V to 2.4 V
Input rise/fall time	10 ns
Input reference level	1.5 V
Output reference level	0.8 V and 2.2 V
Output load condition	1TTL +100 pF

CAPACITANCE (VCC = 5 V ± 10%, f = 1 MHz, TA = 25°C)

PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Input capacitance	CIN			8	pF
Output capacitance	COUT			12	pF

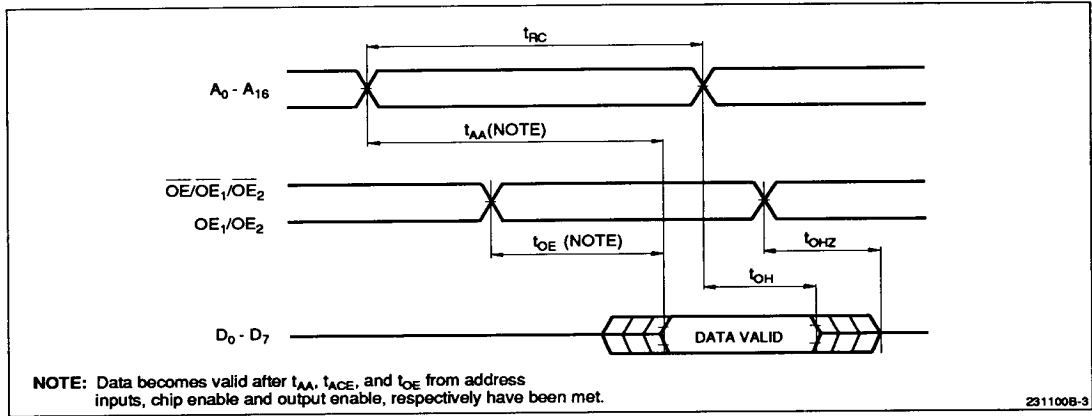


Figure 3. Timing Diagram

ORDERING INFORMATION

LH231100B Device Type	D Package	- ## Speed
		20 200 Access Time (ns)
		32-pin, 600-mil DIP (DIP32-P-600)
		NMOS 1M (128K x 8) Mask Programmable ROM
Example: LH231100BD-20 (NMOS 1M (128K x 8) Mask Programmable ROM, 200 ns, 32-pin, 600-mil DIP)		